



More details here

Storage SuperServer ASG-2117S7-NE332R

2U single socket Petascale with up to 40 hot-swap drive bays and 3 PCIe 6.0 x16 slots + 1 PCIe 6.0 x16 AIOM slot

Key Applications

Virtualization, Software-defined Storage, AI Inference and Machine Learning, Cloud Computing, Enterprise Server, High Performance Computing (HPC),

Key Features

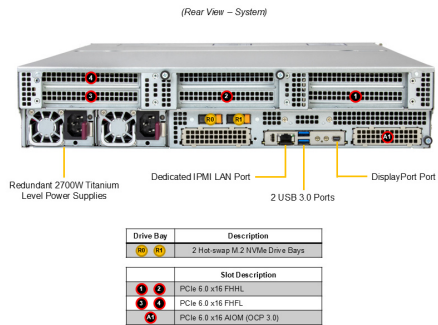
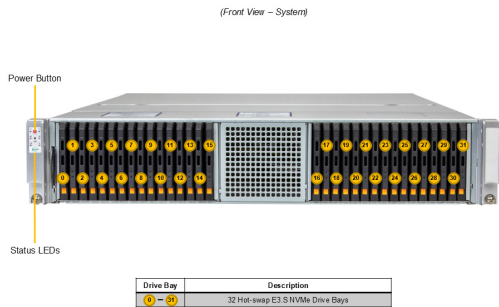
- Single AMD EPYC™ 9006 Series Processor up to 600W with air cooling;
- Up to 16 DIMMs supporting up to 4TB RDIMM DDR5-8000 in 1DPC or 4TB MRDIMM DDR5-12800 in 1DPC;
- Gen6 Networking Support in both AOC and AIOM Format;
- 1x PCIe 6.0 x16 TSFF AIOM (OCP 3.0) ; 2x PCIe 6.0 x16 FHHL slots; 1x PCIe 6.0 x16 FHFL Double-Width slot; 1x PCIe 4.0 x4 DC-SCM;
- Upto 32x Hot Pluggable E3.S or E3.L Drive Slots in Front, and 2x Hot Pluggable 80mm M.2 slots in rear;
- 2 Redundant 2000W Titanium Level power supplies
2 Redundant 2700W Titanium power supplies;
- 2U Rackmount chassis with 30.6" (778 mm) depth;



Form Factor	2U Rackmount Enclosure: 438 x 88 x 780mm (17.25" x 3.47" x 30.7") Package: 597 x 239 x 1097mm (23.5" x 9.4" x 43.2")
Processor	Single processor(s) AMD EPYC™ 9006 SP7 Series Processors Up to 256C/512T
GPU	1 double-width GPU
System Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 8000MT/s ECC DDR5 RDIMM/3DS RDIMM Max Memory (1DPC): Up to 4TB 12800MT/s ECC DDR5 MRDIMM
Drive Bays Configuration	Option A: Total 40 bays • 40 front hot-swap E3.S 1T PCIe 6.0 x2 NVMe drive bays Option B: Total 40 bays • 40 front hot-swap E3.L 1T PCIe 6.0 x2 NVMe drive bays Option C: Total 24 bays • 24 front hot-swap E3.S 1T PCIe 6.0 x4 NVMe drive bays Option D: Total 24 bays • 24 front hot-swap E3.L 1T PCIe 6.0 x4 NVMe drive bays M.2: 2 M.2 PCIe 4.0 x4 NVMe slots (M-key 2280/22110)
Expansion Slots	PCI-Express (PCIe) Configuration: Option A* • 2 PCIe 6.0 x16 (in x16) FHHL double-width slots • 1 PCIe 6.0 x16 (in x16) FHFL double-width slot Option B* • 1 PCIe 6.0 x16 (in x16) FHHL double-width slot • 1 PCIe 6.0 x16 (in x16) FHFL double-width slot Default • 2 PCIe 6.0 x16 (in x16) FHHL double-width slots • 1 PCIe 6.0 x16 (in x16) AIOM slot (OCP 3.0 compatible) M.2: 2 M.2 PCIe 4.0 x4 NVMe slots (M-key)
On-Board Devices	SAS: SAS (12Gbps) via Broadcom® 3808; RAID 0/1 support IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support

Input / Output

LAN: 1 RJ45 1 GbE Dedicated BMC LAN port
USB: 2 USB 3.0 ports (rear)
Video: 1 VGA port
TPM: 1 TPM header



System Cooling	Fans: 6 counter-rotating 60x60x56mm Fan(s) Air Shroud: 1 Air Shroud
Power Supply	2x 2700W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 64MB SPI Flash EEPROM BIOS Features: Plug and Play (PnP) - UEFI 2.8 - USB Keyboard support - ACPI 6.5 - SMBIOS 3.7 or later
Management	SuperCloud Composer® (SCC); Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); KVM with dedicated LAN ; IPMI 2.0; Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!; IPMIView
PC Health Monitoring	Fan: Fans with tachometer monitoring - Pulse Width Modulated (PWM) fan connectors - Status monitor for speed control Temperature: Monitoring for CPU and chassis environment - Thermal Control for fan connectors Voltage: System temperature, Memory temperature, CPU temperature, 3.3V standby, +5V standby, +5V, +3.3V, +12V, CPU thermal trip support
Dimensions and Weight	Weight: Gross Weight: 83.78 lbs (38 kg) Net Weight: 61.73 lbs (28 kg) Available Color: Silver
Operating Environment	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super H15SPF
Chassis	CSE-256E3-R000NDP